



## Product/Process Change Notice - PCN 14\_0259 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

**PCN Title:** Assembly Transfer of Select 10x10 and 14x14 TQFP\_EP Products to Amkor Philippines

**Publication Date:** 10-Dec-2014

**Effectivity Date:** 01-May-2015 *(the earliest date that a customer could expect to receive changed material)*

### Revision Description:

Initial Release

### Description Of Change

ADI is transferring to qualified subcontractor Amkor Philippines for the assembly of 10x10 and 14x14 TQFP\_EP products. ADI will be qualifying Amkor's standard bill of materials(BOM). The mold compound material for 14x14 body packages will change from Sumitomo G700L to Sumitomo G631HQ. The mold gate position will change as a result of the mold compound change. The package outline dimensions and wire sizes of each product will be maintained.

### Reason For Change

ADI is transferring to Amkor Philippines due to the closure of Amkor Korea factory lines in October 2015 for 10x10 TQFP\_EP and November 2015 for 14x14 TQFP\_EP.

ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability.

### Impact of the change (positive or negative) on fit, form, function & reliability

The transfer will have no impact on the form, fit, function and reliability of the devices.

### Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled after the transfer will be identified by assembly lot number and the country of origin.

### Summary of Supporting Information

Qualification will be performed per AEC-Q100, Stress Test Qualification for Integrated Circuits. See attached Qualification Plans.

### Supporting Documents

**Attachment 1: Type:** Detailed Parts List

ADI\_PCN\_14\_0259\_Rev\_-\_TQFP\_EP\_10x10\_14x14\_PART\_LIST\_REV\_A.docx

**Attachment 2: Type:** Qualification Plan

**Attachment 3: Type:** Qualification Plan

ADI\_PCN\_14\_0259\_Rev\_-\_10x10 TQFP\_EP Using G700L\_3230 at AP\_Automotive.docx

**For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.**

**Americas:** [PCN\\_Americas@analog.com](mailto:PCN_Americas@analog.com)

**Europe:** [PCN\\_Europe@analog.com](mailto:PCN_Europe@analog.com)

**Japan:** [PCN\\_Japan@analog.com](mailto:PCN_Japan@analog.com)

**Rest of Asia:** [PCN\\_ROA@analog.com](mailto:PCN_ROA@analog.com)

**Appendix A - Affected ADI Models**

**Added Parts On This Revision - Product Family / Model Number (7)**

|                           |                            |                        |                           |                        |
|---------------------------|----------------------------|------------------------|---------------------------|------------------------|
| AD8284 / AD8284WCSVZ      | ADAU1442 / ADAU1442YSVZ-3A | ADAU1442 / ADW8000YSVZ | ADAU1442 / ADW8000YSVZ-RL | ADAU1445 / ADW8000YSVZ |
| ADAU1445 / ADW8000YSVZ-RL | ADAU1445 / ADW80009BSVZ    |                        |                           |                        |

**Appendix B - Revision History**

| <b>Rev</b> | <b>Publish Date</b> | <b>Effectivity Date</b> | <b>Rev Description</b> |
|------------|---------------------|-------------------------|------------------------|
| Rev. -     | 10-Dec-2014         | 01-May-2015             | Initial Release        |
|            |                     |                         |                        |

Analog Devices, Inc.

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